Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138 PRODUCT/PROCESS CHANGE NOTICE (PCN)						
PCN #: A1711-02	DATE: 13-Nov-2017	MEANS OF	DISTINGUISHING CHANGED DEVICES:			
Product Affected: TQFP-128 (Refer to Attachment II for the af	ffected part numbers)	 Product Back Ma Date Cool Other 	rk Lot # will have:			
Date Effective: 13-Feb-2018						
Contact: IDT PCN DESK		Attachment	Yes No			
E-mail: pcndesk@idt.com		Samples:	Please contact your local sales representative for sample request.			
DESCRIPTION AND PURPOSE OF CH	ANGE:					
 □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Assembly Process This notification is to advise our customers that IDT is adding Greatek, Taiwan as an alternate assembly facility for parts that are currently assembled at Amkor Philippines.						
□ Equipment The The	There is no change to the moisture performance.					
Testing Atta	Attachment I details the qualification results and Attachment II shows the affected list of part numbers.					
RELIABILITY/QUALIFICATION SUM Refer to qualification data shown in Attach						
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.						
Customer:		Approv	al for shipments prior to effective date.			
Name/Date:	E-	Mail Addres	s:			
Title:	Ph	none#/Fax# :				
CUSTOMER COMMENTS:						
IDT ACKNOWLEDGMENT OF RECEI	(PT:					
RECD. BY:		DATE:				



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1711-02

PCN Type:	Manufacturing Site - Alternate Assembly Location		
Data Sheet Change:	None		
	No change in moisture sensitivity level (MSL)		

Detail Of Change:

This notification is to advise our customers that IDT is adding Greatek, Taiwan as an alternate assembly facility for parts that are currently assembled at Amkor Philippines.

The material set details of the current and the alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing Assembly (Amkor, Philippines)	Alternate Assembly (Greatek, Taiwan)
Die Attach	3230	CRM1076
Bond Wire	Gold wire	Gold wire
Mold Compound	G700Y	G700H



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ATTACHMENT I - PCN # : A1711-02

Qualification Information and Qualification Data:

- Affected Packages: TQFP-128
- Assembly Material: Shown on page 2 of this attachment.
- Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: TQFP-128

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Test Description	Test Method	Test Results (Rej / SS)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (Vccmax, 130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
X Ray	IDT Spec. MAC- 3012	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN # : A1711-02

Part Number	Part Number	Part Number	Part Number
89HMPEB383ZAEMG	89HMPEB383ZBEMG	89HPEB383ZAEMG	89HPEB383ZBEMG
89HMPEB383ZAEMG8	89HMPEB383ZBEMG8	89HPEB383ZAEMG8	89HPEB383ZBEMG8